AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) An electronic device comprising:

[[a]] an airtight sealed housing sealing a fixed amount of air within the housing;

an electrical circuit component in said sealed housing; and

a movable fin that protrudes to the outside of said sealed housing, outward movement of the fin being caused by ~~depending on~~ a rise in internal temperature of said sealed housing.

2. (currently amended) An electronic device as claimed in claim 1, wherein,

said movable fin protrudes to the outside of said sealed housing through a guide hole formed in said sealed housing, and has airtightness means between itself and said guide hole, and

the outward movement of the fin depends on an atmospheric pressure increase inside the sealed housing acting against a housing inner side of the fin.

3. (currently amended) An electronic device as claimed in claim 1, wherein a heat generating portion of a package or the like mounted therein with said electrical circuit component and said movable fin are connected to each other by a flexible sheet, and

an internal calorific value increase of the housing causes an atmospheric pressure increase inside the sealed housing and the increased atmospheric pressure acts against a housing inner side of the fin to provide a force causing the outward movement of the fin.

4. (currently amended) An electronic device as claimed in claim 2, wherein a heat generating portion of a package or the like mounted therein with said electrical circuit component and said movable fin are connected to each other by a flexible sheet, and

further comprising a return spring located intermediate the housing and the fin, the return spring acting to move the fin into the housing.

5. (withdrawn) An electronic device as claimed in claim 1, wherein said movable fin is caused to protrude to the outside of said sealed housing by a member that returns to its original shape at a set temperature.

6. (withdrawn) An electronic device as claimed in claim 2, wherein said movable fin is caused to protrude to the outside of said sealed housing by a member that returns to its original shape at a set temperature.

7. (withdrawn) An electronic device as claimed in claim 3, wherein said movable fin is caused to protrude to the outside of said sealed housing by a member that returns to its original shape at a set temperature.

8. (withdrawn) An electronic device as claimed in claim 4, wherein said movable fin is caused to protrude to the outside of said sealed housing by a member that returns to its original shape at a set temperature.

9. (withdrawn) An electronic device comprising:

a sealed housing;

an electrical circuit component in said sealed housing; and

a bellows container with a variable internal volume that is connected between a first hole in an upper part of said sealed housing and a second hole in a lower part thereof.

10. (withdrawn) An electronic device comprising:

a sealed housing;

an electrical circuit component in said sealed housing; and

an expandable/contractible balloon that is connected between a first hole in an upper part of said sealed housing and a second hole in a lower part thereof.

11. (currently amended) A heat radiation method for an electronic device having a sealed housing, wherein, when an internal temperature of said sealed housing having therein an electrical circuit component rises, a movable fin is caused to protrude to the outside of said sealed housing, wherein, an internal calorific value increase of the housing causes an atmospheric pressure increase inside the sealed housing and the increased atmospheric pressure acts against a housing inner side of the fin to provide a force causing the outward movement of the fin.

12. (original) A heat radiation method for an electronic device having a sealed housing as claimed in claim 11, wherein said movable fin is caused to protrude through a guide hole formed in said sealed housing, while keeping airtightness.

13. (original) A heat radiation method for an electronic device having a sealed housing as claimed in claim 11, wherein heat of a package or the like mounted therein with said

electrical circuit component is conducted to said movable fin by a flexible sheet.

14. (original) A heat radiation method for an electronic device having a sealed housing as claimed in claim 12, wherein heat of a package or the like mounted therein with said electrical circuit component is conducted to said movable fin by a flexible sheet.

15. (withdrawn, currently amended) A heat radiation method for an electronic device having a sealed housing as claimed in claim 11, wherein said movable fin is further caused to protrude by deformation of a member due to a temperature increase of said member, said member adapted to return to its original shape upon a following decrease in the temperature of said member.

16. (withdrawn, currently amended) A heat radiation method for an electronic device having a sealed housing as claimed in claim 12, wherein said movable fin is further caused to protrude by deformation of a member due to a temperature increase in said member, said member adapted to return to its original shape upon a following decrease in the temperature of said member.

17. (withdrawn, currently amended) A heat radiation method for an electronic device having a sealed housing as claimed in claim 13, wherein said movable fin is further caused to protrude by deformation of a member due to a temperature increase of said member, said member adapted to return to its original shape.

18. (withdrawn, currently amended) A heat radiation method for an electronic device having a sealed housing as claimed in claim 14, wherein said movable fin is further caused to protrude by deformation of a member due to a temperature increase in said member, said member adapted to return to its original shape.

19-20. (canceled)

21. (currently amended) A sealed airtight housing of an electronic device, comprising:

a sealed airtight housing sealing a fixed amount of air within the housing;

a guide hole within an exterior surface of the housing; and

a movable fin that protrudes to the outside of the housing through said guide hole, an outward movement of the fin depending on a rise in internal pressure of the fixed amount of

air, the rise in internal pressure caused by a rise in internal temperature of said sealed housing.

22. (original) A sealed housing of an electronic device as claimed in claim 21, wherein said movable fin has airtightness means between itself and said guide hole.

23. (original) A sealed housing of an electronic device as claimed in claim 21, further comprising a flexible sheet connecting between a heat generating portion mounted in said sealed housing and said movable fin.

24. (original) A sealed housing of an electronic device as claimed in claim 22, further comprising a flexible sheet connecting between a heat generating portion mounted in said sealed housing and said movable fin.

25. (withdrawn, currently amended) A sealed housing of an electronic device as claimed in claim 21, wherein said movable fin is further caused to protrude to the outside by a member that returns to its original shape at a set temperature.

26. (withdrawn, currently amended) A sealed housing of an electronic device as claimed in claim 22, wherein said movable

fin is further caused to protrude to the outside by a member that returns to its original shape at a set temperature.

27. (withdrawn, currently amended) A sealed housing of an electronic device as claimed in claim 23, wherein said movable fin is further caused to protrude to the outside by a member that returns to its original shape at a set temperature.

28. (withdrawn, currently amended) A sealed housing of an electronic device as claimed in claim 24, wherein said movable fin is further caused to protrude to the outside by a member that returns to its original shape at a set temperature.

29-30. (canceled)

31. (new) An electronic device, comprising:

an airtight sealed housing sealing a fixed amount of air within the housing;

an electrical circuit component in said sealed housing; and

a movable heat radiation fin that protrudes to the outside of the sealed housing, outward movement of the fin being caused by a rise in internal pressure of the sealed air acting on an housing inside surface of the fin, wherein,

heat generated by the electrical circuit component causes an increase of an internal temperature of the sealed housing and the increased internal temperature of the sealed housing causes the increase in internal pressure of the sealed air.

32. (new) An electronic device, comprising:

a body and a cover joined together via a packing to form a sealed housing that airtight seals a fixed amount of air within the housing;

a board, attached with a package having electrical circuit components mounted thereon, mounted to the housing;

movable heat radiation fins that protrudes to the outside of the sealed housing, outward movement of the fins being caused by a rise in internal pressure of the sealed air acting on an housing inside surface of the fin; and

a heat conductive member, wherein,

the package is in contact with an inner periphery of heat radiation fins forming part of an inner periphery of the body, via the heat conductive member, the contact providing a path to radiate heat generated by the electrical circuit components, and

heat generated by the electrical circuit component causes an increase of an internal temperature of the housing and

the increased internal temperature of the sealed housing causes the increase in internal pressure of the sealed air.

33. (new) An electronic device, comprising:

a body and a cover joined together via a packing to form a sealed housing that airtight seals a fixed amount of air within the housing;

a board, attached with a package having electrical circuit components mounted thereon, mounted to the housing;

movable heat radiation fins that protrudes to the outside of the sealed housing, outward movement of the fins being caused by a rise in internal pressure of the sealed air acting on an housing inside surface of the fins; and

a heat conductive member, wherein,

the package is in contact with an inner periphery of heat radiation fins forming part of an inner periphery of the body, via the heat conductive member, the contact providing a path to radiate heat generated by the electrical circuit components.

34. (new) An electronic device, comprising:

a body and a cover joined together and forming a sealed housing that airtight seals a fixed amount of air within the housing;

a board, attached with a package having electrical circuit components mounted thereon, mounted to the housing; and

movable heat radiation fins protruding through an outside of the cover, outward movement of the fins being caused by a rise in an internal pressure acting on an housing inside surface of the fins.

35. (new) The device of claim 34, further comprising:

return springs located intermediate the cover and each fin, the return springs acting to move the fins into the housing.